

MOLDING POWER INDUCTORS HIGH CURRENT INDUCTORS





•FEATURE

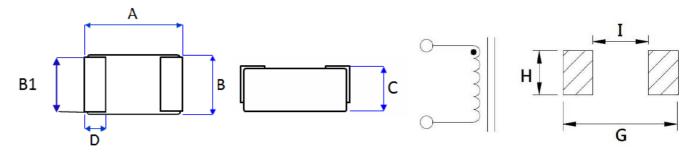
- 1. Shielded construction(height=1.20mm Max)
- 2. Frequency range up to 5MHz, Low DCR(Ω)

Applications

1. Notebook, server application, High current power supplier

● Shape and Dimension

Schematics and Land Patterns(mm)



 $A=2.0\pm0.2$ m/m ; $B=1.6\pm0.2$ m/m ; $B1=1.5\pm0.2$ m/m; C=1.20m/m Max. ; $D=0.5\pm0.3$ m/m G=2.3m/m Ref. ; H=1.6m/m Ref. ; I=0.9m/m Ref.

Specification

| P/N | L (µH) | RDC(mΩ) Max | Isat (A) | Irms (A) |
|-----------------|----------|-------------|----------|----------|
| EPIC201612-R24M | 0.24±20% | 21 | 4.8 | 4.0 |
| EPIC201612-R33M | 0.33±20% | 33 | 4.0 | 3.5 |
| EPIC201612-R47M | 0.47±20% | 36 | 3.5 | 3.1 |
| EPIC201612-R68M | 0.68±20% | 55 | 3.0 | 2.6 |
| EPIC201612-1R0M | 1.0±20% | 72 | 2.5 | 2.2 |
| EPIC201612-1R5M | 1.5±20% | 112 | 2.2 | 1.7 |
| EPIC201612-2R2M | 2.2±20% | 186 | 1.9 | 1.5 |

Note1. Measurement frequency of Inductance value: at 1MHz, 1V

Note3. Isat: DC current at which the inductance drops 30%(typ) from its value without current

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GENERAL CHARACTERISTICS

- 1. Operating temperature range: -55 TO + 125°C (Includes temperature when the coil is heated)
- 2. External appearance: On visual inspection, the coil has no external defects.
- Terminal strength: After soldering. Between copper plate and terminals of coil. Push in two directions of X.Y withstanding at below conditions.

Terminal should not peel off. (refer to figure at right) 5. 0N 60 sec.

- 4. Insulating resistance: Over $100M\Omega$ at 100V D.C. between coil and core.
- 5. Dielectric strength: No dielectric breakdown at 100V D.C. for 1 minute between coil and core.
- 6. Temperature characteristics: Inductance coefficient (0~2,000)x10-6/℃ (-25~+80℃ degree Celsius), inductance deviation within±5.0%, after 96 hours.
- 7. Humidity characteristics(Moisture Resistance): Inductance deviation within ±5%, after 96 hours in 90~95% relative humidity at 40 ±2°C and 1 hour drying under normal condition.
- 8. Vibration resistance: Inductance deviation within ±5%, after vibration for 1 hour. In each of three orientations at sweep vibration (10~55~10 Hz) with 1.5mm P-P amplitudes.
- 9. Shock resistance: Inductance deviation within ±5%, after being dropped once with 981m/s2 (100G) shock attitude upon a rubber block method shock testing machine, in three different orientations.
- 10. Resistance to Soldering Heat: 260°C, 10 seconds(See attached recommend reflow)
- 11. Storage condition: Temperature Range: 0° C $\sim 35^{\circ}$ C ; -55° C $\sim 125^{\circ}$ C (after PCB) , Humidity Range: 50% $\sim 70\%$ RH
- 12. Use components within 12 months. If 12 months or more have elapsed, check solderability before use.
- 13. Reflow profile recommend:

Lead-free heat endurance test

Lead-free the recommended reflow condition

